

Abstract of the Disclosure

A wet cleaning or wet etch facility for semiconductor wafers includes a plurality of chemical baths into which wafers are dipped, a drying unit for drying the wafers, a robot arm that transports the wafers to the plurality of the chemical baths and the drying unit in sequence, and a bubble-detecting sensor for detecting the amount of bubbles generated by the chemicals. A central control unit stops the wet cleaning or wet etch process for a while when the amount of bubbles produced by the chemical exceeds a predetermined amount.